PXIe-5775 Specifications



Contents

DYIA-5775 S	ecifications	-
I VIC-21122	zanications	_

PXIe-5775 Specifications

Definitions

Warranted specifications describe the performance of a model under stated operating conditions and are covered by the model warranty.

Characteristics describe values that are relevant to the use of the model under stated operating conditions but are not covered by the model warranty.

- *Typical* specifications describe the performance met by a majority of models.
- **Nominal** specifications describe an attribute that is based on design, conformance testing, or supplemental testing.
- *Measured* specifications describe the measured performance of a representative model.

Specifications are *Typical* unless otherwise noted.

Digital I/O

Connector	Molex™ Nano-Pitch I/O™
5.0 V Power	±5%, 50 mA maximum, nominal

Table 1. Digital I/O Signal Characteristics

Signal	Туре	Direction
MGT Tx± <03> $[1]$	Xilinx UltraScale GTH	Output
MGT Rx± <03> ^[1]	Xilinx UltraScale GTH	Input
DIO <07>	Single-ended	Bidirectional

Signal	Туре	Direction
5.0 V	DC	Output
GND	Ground	_

Digital I/O Single-Ended Channels

Number of channels	8
Signal type	Single-ended
Voltage families	3.3 V, 2.5 V, 1.8 V, 1.5 V, 1.2 V
Input impedance	100 kΩ, nominal
Output impedance	50 Ω, nominal
Direction control	Per channel
Minimum required direction change latency	200 ns
Maximum output toggle rate	60 MHz with 100 μA load, nominal

Table 2. Digital I/O Single-Ended DC Signal Characteristics $^{[2]}$

Voltage Family (V)	V _{IL} (V)	V _{IH} (V)	V _{OL} (100 μA Load) (V)	V _{OH} (100 μA Load) (V)	Maximum DC Drive Strength (mA)
3.3	0.8	2.0	0.2	3.0	24
2.5	0.7	1.6	0.2	2.2	18

Voltage Family (V)	V _{IL} (V)	V _{IH} (V)	V _{OL} (100 μA Load) (V)	V _{OH} (100 μA Load) (V)	Maximum DC Drive Strength (mA)
1.8	0.62	1.29	0.2	1.5	16
1.5	0.51	1.07	0.2	1.2	12
1.2	0.42	0.87	0.2	0.9	6

Digital I/O High-Speed Serial MGT^[3]



Note MGTs are available on devices with KU040 and KU060 FPGAs only.

Data rate	500 Mbps to 16.375 Gbps, nominal
Number of Tx channels	4
Number of Rx channels	4
I/O AC coupling capacitor	100 nF

MGT TX± Channels^[4]

Minimum differential output voltage ^[5]	170 mV pk-pk into 100 Ω , nominal
I/O coupling	AC-coupled, includes 100 nF capacitor

MGT RX± Channels

Differential input voltage range	
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≤ 6.6 Gb/s	150 mV pk-pk to 2000 mV pk-pk, nominal		
> 6.6 Gb/s	150 mV pk-pk to 1250 mV pk-pk, nominal		
Differential input resistance		100 Ω , nominal	
I/O coupling		DC-coupled, requires external capacitor	

Reconfigurable FPGA

PXIe-5775 modules are available with multiple FPGA options. The following table lists the FPGA specifications for the PXIe-5775 FPGA options.

Table 3. Reconfigurable FPGA Options

	KU035	KU040	KU060
LUTs	203,128	242,200	331,680
DSP48 slices (25 × 18 multiplier)	1,700	1,920	2,760
Embedded Block RAM	19.0 Mb	21.1 Mb	38.0 Mb
Data Clock Domain	200 MHz, 16 samples per cycle per channel (dual channel mode), 32 samples per cycle (single channel mode)		
Timebase reference sources	PXI Express 100 MHz (PXIe_CLK100)		
Data transfers	DMA, interrupts, programmed I/O, programmed I/O multi-gigabit transceivers		
Number of DMA 60 channels			



Note The Reconfigurable FPGA Options table depicts the total number of

FPGA resources available on the part. The number of resources available to the user is slightly lower, as some FPGA resources are consumed by boardinterfacing IP for PCI Express, device configuration, and various board I/O. For more information, contact NI support.

Onboard DRAM

Memory size	4 GB (2 banks of 2 GB)
DRAM clock rate	1064 MHz
Physical bus width	32 bit
LabVIEW FPGA DRAM clock rate	267 MHz
LabVIEW FPGA DRAM bus width	256 bit per bank
Maximum theoretical data rate	17 GB/s (8.5 GB/s per bank)

Analog Input

General Characteristics

Number of channels	2, single-ended, simultaneously sampled
Connector type	SMA

Input impedance	50 Ω	50 Ω		
Input coupling	AC	AC		
Sample Clock				
Internal Sample Clock			3.2 GHz	
External Sample Clock	lock		2.8 GHz to 3.2 GHz	
Sample Rate				
Dual channel mode		3.2 GS/s per channel		
Single channel mode		6.4 GS/s		
Analog-to-digital converter (ADC)	ADC12DJ3200, 12-bit resolution			
Input latency ^[6]	239 ns			

Typical Specifications

Full-scale input range	1.25 V pk-pk (5.92 dBm) at 10 MHz
AC gain accuracy	±0.11 dB at 10 MHz
DC offset	±2.19 mV

Bandwidth (-3 dB) ^[7]	500 kHz to 6 GHz
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Table 4. Single-Tone Spectral Performance, Dual Channel Mode

	Input Frequency				
	99.9 MHz	399 MHz	999 MHz	1.999 GHz	2.499 GHz
SNR ^[8] (dBFS)	56.0	55.6	54.7	52.9	51.6
SINAD ^[8] (dBFS)	55.5	55.0	54.0	51.8	50.8
SFDR (dBc)	-64.9	-63.4	-62.7	-59.9	-58.6
ENOB ^[9] (bits)	8.9	8.8	8.7	8.3	8.1

Table 5. Single-Tone Spectral Performance, Single Channel $\mathsf{Mode}^{[10]}$

	, ,				
	Input Frequency				
	99.9 MHz	99.9 MHz 399 MHz 999 MHz 1.999 GHz 2.499 GH			
SNR ^[8] (dBFS)	54.6	54.2	52.4	49.7	48.9
SINAD ^[8] (dBFS)	54.4	53.9	52.1	49.4	48.6
SFDR (dBc)	-61.7	-60.4	-56.1	-51.7	-51.1
ENOB ^[9] (bits)	8.7	8.7	8.4	7.9	7.8

Table 6. Noise Spectral Density $^{[11]}$

Mode	$\frac{nV}{\sqrt{Hz}}$	dBm Hz	dBFS Hz
Dual channel	14.4	-143.8	-149.2
Single channel	9.8	-147.2	-152.6



Note Noise spectral density is verified using a 50 Ω terminator connected to

Figure 1. Single Tone Spectrum (Dual Channel Mode, 99.9 MHz, -1 dBFS, 3.2 kHz RBW), Measured

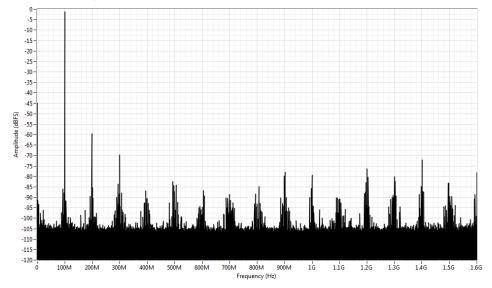


Figure 2. Single Tone Spectrum (Dual Channel Mode, 1.999 GHz, -1 dBFS, 3.2 kHz RBW), Measured

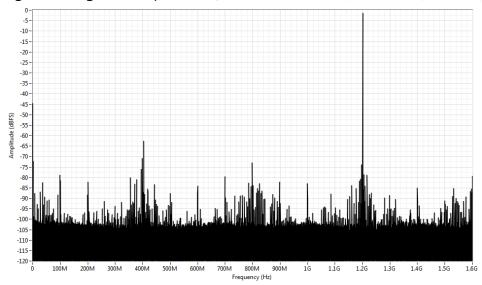


Figure 3. Single Tone Spectrum (Single Channel Mode, 99.9 MHz, -1 dBFS, 3.2 kHz RBW), Measured

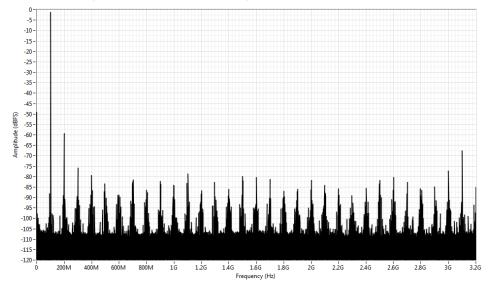
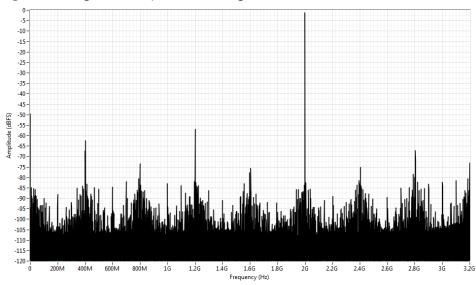


Figure 4. Single Tone Spectrum (Single Channel Mode, 1.999 GHz, -1 dBFS, 3.2 kHz RBW), Measured



Channel-to-channel crosstalk, measured		
99.9 MHz	-92.5 dB	
399 MHz	-85.5 dB	
999 MHz	-76.5 dB	

1.999 GHz	-68.8 dB
2.499 GHz	-67.4 dB

Figure 5. Analog Input Frequency Response, Measured

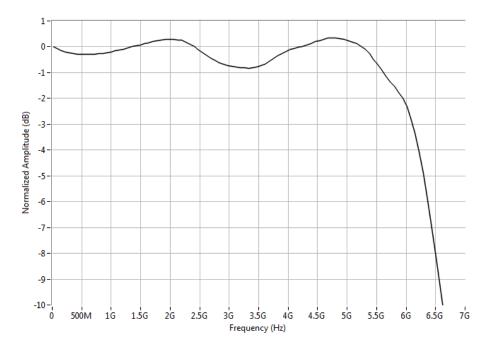
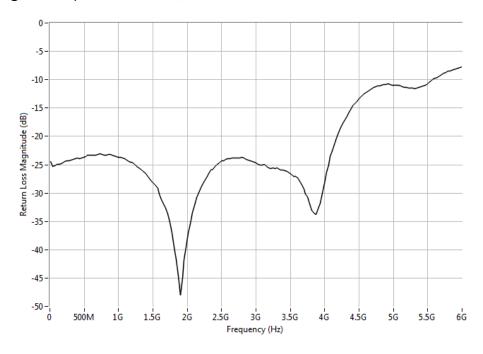


Figure 6. Input Return Loss, Measured



CLK/REF IN

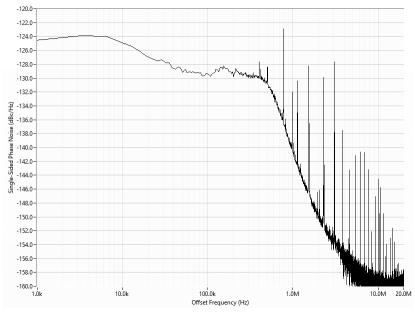
Connector type	SMA
Input impedance	50 Ω
Input coupling	AC
Input voltage range	0.35 V pk-pk to 3.5 V pk-pk
Absolute maximum voltage	±12 V DC, 4 V pk-pk AC
Duty cycle	45% to 55%

Sample Clock jitter ^[12]	86.8 fs RMS, measured
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Table 7. Clock Configuration Options

Clock Configuration	External Clock Frequency	Description
Internal PXI_CLK10 ^[13]	10 MHz	The internal Sample Clock locks to the PXI 10 MHz Reference Clock, which is provided through the backplane.
External Reference Clock (CLK/ REF IN)	10 MHz ^[14]	The internal Sample Clock locks to an external Reference Clock, which is provided through the CLK/REF IN front panel connector.
External Sample Clock (CLK/ REF IN)	2.0 GHz to 3.2 GHz	An external Sample Clock can be provided through the CLK/ REF IN front panel connector.

Figure 7. Phase Noise with 800 MHz Input Tone, Measured



Bus Interface

Form factor	PCI Express Gen-3 x8

Maximum Power Requirements



 $oldsymbol{Note}$ Power requirements depend on the contents of the LabVIEW FPGA VI used in your application.

+3.3 V	3 A
+12 V	4 A
Maximum total power	58 W

Physical

Dimensions (not including connectors)	18.8 cm × 12.9 cm (7.4 in. × 5.1 in.)
Weight	190 g (6.7 oz)

Environment

Maximum altitude	2,000 m (800 mbar) (at 25 °C ambient temperature)
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Pollution Degree 2

Indoor use only.

Operating Environment

Ambient temperature range	0 °C to 55 °C $^{[15]}$ (Tested in accordance with IEC 60068-2-1 and IEC 60068-2-2. Meets MIL-PRF-28800F Class 3 low temperature limit and MIL-PRF-28800F Class 2 high temperature limit.)
Relative humidity range	10% to 90%, noncondensing (Tested in accordance with IEC 60068-2-56.)

Storage Environment

Ambient temperature range	-40 °C to 71 °C (Tested in accordance with IEC 60068-2-1 and IEC 60068-2-2. Meets MIL-PRF-28800F Class 4 limits.)
Relative humidity range	5% to 95%, noncondensing (Tested in accordance with IEC 60068-2-56.)

Shock and Vibration

Operating shock	30 g peak, half-sine, 11 ms pulse
Random vibration	

Operating	5 Hz to 500 Hz, 0.3 g _{rms}
Nonoperating	5 Hz to 500 Hz, 2.4 g _{rms}

NI-TClk

You can use the NI-TClk synchronization method and the NI-TClk driver to align the Sample Clocks on any number of supported devices in one or more chassis. For more information about TClk synchronization, refer to the NI-TClk Synchronization **Help** within the **FlexRIO Help**. For other configurations, including multichassis systems, contact NI Technical Support at ni.com/support.

Intermodule Synchronization Using NI-TClk for Identical Modules

Synchronization specifications are valid under the following conditions:

- All modules are installed in one PXI Express chassis.
- The NI-TClk driver is used to align the Sample Clocks of each module.
- All parameters are set to identical values for each module.
- Modules are synchronized without using an external Sample Clock.



Note Although you can use NI-TClk to synchronize non-identical modules, these specifications apply only to synchronizing identical modules.

Skew ^[16]	80 ps, measured
Skew after manual adjustment	≤10 ps, measured
Sample Clock delay/adjustment	0.4 ps